



### General Description

AFC4614WS, N & P Pair enhancement mode MOSFET, uses Advanced Trench Technology to provide excellent  $R_{DS(ON)}$ , low gate charge. These devices are particularly suited for low voltage power management, and low in-line power loss are needed in commercial industrial surface mount applications.

### Features

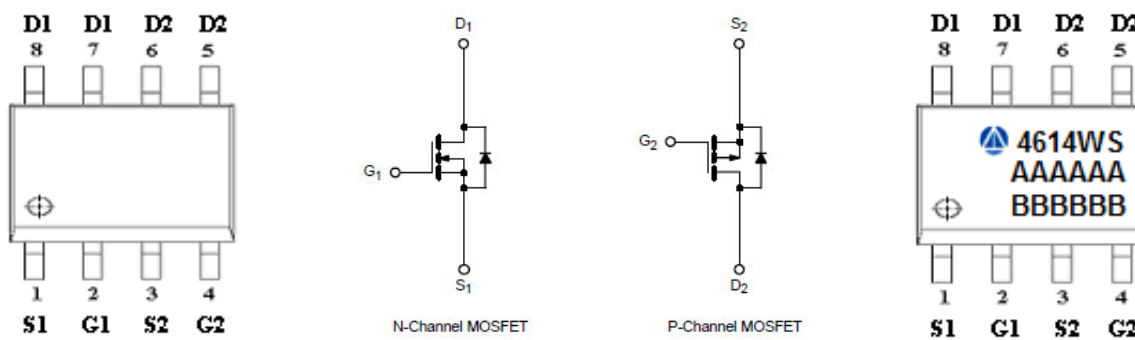
N-Channel

- 40V/10A,  $R_{DS(ON)} = 35m\Omega @ V_{GS} = 10V$
- 40V/6A,  $R_{DS(ON)} = 45m\Omega @ V_{GS} = 4.5V$

P-Channel

- -40V/-10A,  $R_{DS(ON)} = 35m\Omega @ V_{GS} = -10V$
- -40V/-6A,  $R_{DS(ON)} = 45m\Omega @ V_{GS} = -4.5V$

### Pin Description ( SOP-8P )



### Application

- Low Current DC/DC Conversion
- Load Switch
- CCFL Inverter
- Power Management in Notebook Computer

### Pin Define

Pin	Symbol	Description
1	S1	N-Source 1
2	G1	N-Gate 1
3	S2	P-Source 2
4	G2	P-Gate 2
5	D2	P-Drain 2
6	D2	P-Drain 2
7	D1	N-Drain 1
8	D1	N-Drain 1

### Ordering Information

Part Ordering No.	Part Marking	Package	Unit	Quantity
AFC4614WSS8RG	4614WS	SOP-8P	Tape & Reel	2500 EA

- ※ A Lot code
- ※ B Date code
- ※ AFC4614WSS8RG : 13" Tape & Reel ; Pb- Free ; Halogen- Free



**Absolute Maximum Ratings ( N-Channel )**

( $T_A=25^{\circ}\text{C}$  Unless otherwise noted)

Parameter	Symbol	Typical	Unit
Drain-Source Voltage	$V_{DSS}$	40	V
Gate –Source Voltage	$V_{GSS}$	$\pm 20$	V
Continuous Drain Current( $T_J=150^{\circ}\text{C}$ )	$I_D$	$T_A=25^{\circ}\text{C}$	10
		$T_A=70^{\circ}\text{C}$	6
Pulsed Drain Current	$I_{DM}$	20	A
Avalanche Current	$L = 0.1 \text{ mH}$	$I_{AS}$	8
Avalanche Energy		$E_{AS}$	3.2
Continuous Source Current(Diode Conduction)	$I_S$	1.6	A
Power Dissipation	$P_D$	$T_A=25^{\circ}\text{C}$	2.8
		$T_A=70^{\circ}\text{C}$	1.8
Operating Junction Temperature	$T_J$	150	$^{\circ}\text{C}$
Storage Temperature Range	$T_{STG}$	-55/150	$^{\circ}\text{C}$
Thermal Resistance-Junction to Ambient	$R_{\theta JA}$	62.5	$^{\circ}\text{C/W}$

**Electrical Characteristics**

( $T_A=25^{\circ}\text{C}$  Unless otherwise noted)

Parameter	Symbol	Conditions	Min.	Typ	Max.	Unit
<b>Static</b>						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0V, I_D=250\mu A$	40			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	1.0		2.5	
Gate Leakage Current	$I_{GSS}$	$V_{DS}=0V, V_{GS}=\pm 20V$			$\pm 100$	nA
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=32V, V_{GS}=0V$			1	uA
		$V_{DS}=32V, V_{GS}=0V$ $T_J=85^{\circ}\text{C}$			10	
On-State Drain Current	$I_{D(on)}$	$V_{DS} \geq 5V, V_{GS}=10V$	8			A
Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS}=10V, I_D=10A$		27	35	m $\Omega$
		$V_{GS}=4.5V, I_D=6A$		33	45	
Forward Transconductance	$g_{FS}$	$V_{DS}=10V, I_D=8A$		27		S
Diode Forward Voltage	$V_{SD}$	$I_S=1.5A, V_{GS}=0V$		0.85	1.2	V
<b>Dynamic</b>						
Total Gate Charge	$Q_g$	$V_{DS}=10V, V_{GS}=4.5V$ $I_D=8A$		3.3	5	nC
Gate-Source Charge	$Q_{gs}$			1		
Gate-Drain Charge	$Q_{gd}$			1.2		
Input Capacitance	$C_{iss}$	$V_{DS}=20V, V_{GS}=0V$ $f=1\text{MHz}$		385		pF
Output Capacitance	$C_{oss}$			68		
Reverse Transfer Capacitance	$C_{rss}$			30		
Turn-On Time	$t_{d(on)}$	$V_{DD}=20V, R_L=2\Omega$ $I_D=8A, V_{GEN}=10V$ $R_G=1\Omega$		9	18	ns
	$t_r$			11	22	
Turn-Off Time	$t_{d(off)}$			10	20	
	$t_f$			7	14	



**Absolute Maximum Ratings ( P-Channel )**

(T<sub>A</sub>=25°C Unless otherwise noted)

Parameter	Symbol	Typical	Unit
Drain-Source Voltage	V <sub>DSS</sub>	-40	V
Gate –Source Voltage	V <sub>GSS</sub>	±20	V
Continuous Drain Current(T <sub>J</sub> =150°C)	I <sub>D</sub>	T <sub>A</sub> =25°C	-10
		T <sub>A</sub> =70°C	-6
Pulsed Drain Current	I <sub>DM</sub>	-20	A
Continuous Source Current(Diode Conduction)	I <sub>S</sub>	-1.7	A
Power Dissipation	P <sub>D</sub>	T <sub>A</sub> =25°C	2.8
		T <sub>A</sub> =70°C	1.8
Operating Junction Temperature	T <sub>J</sub>	150	°C
Storage Temperature Range	T <sub>STG</sub>	-55/150	°C
Thermal Resistance-Junction to Ambient	R <sub>θJA</sub>	62.5	°C/W

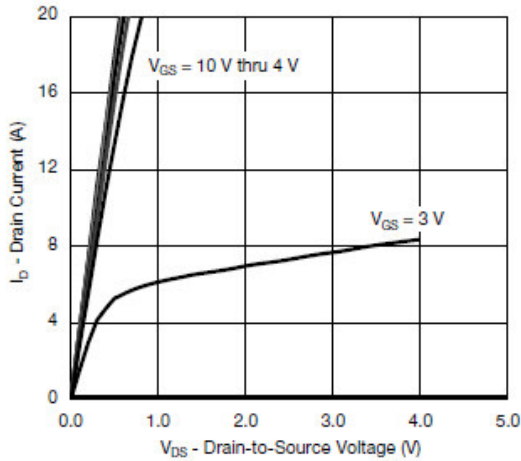
**Electrical Characteristics**

(T<sub>A</sub>=25°C Unless otherwise noted)

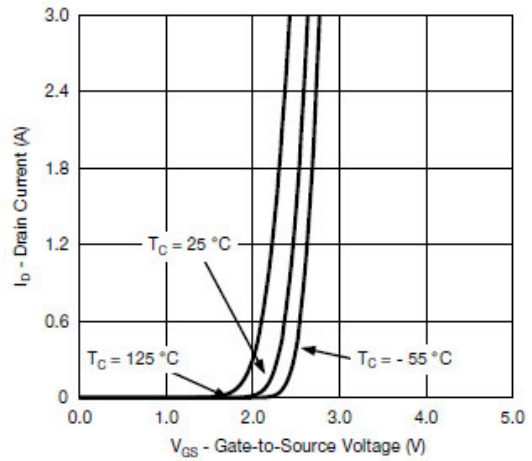
Parameter	Symbol	Conditions	Min.	Typ	Max.	Unit
<b>Static</b>						
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> = -250uA	-40			V
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> = -250uA	-1.0		-3.0	
Gate Leakage Current	I <sub>GSS</sub>	V <sub>DS</sub> =0V, V <sub>GS</sub> = ±20V			±100	nA
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = -40V, V <sub>GS</sub> =0V			-1	
		V <sub>DS</sub> = -40V, V <sub>GS</sub> =0V T <sub>J</sub> =85°C			-20	uA
On-State Drain Current	I <sub>D(on)</sub>	V <sub>DS</sub> ≥ -5V, V <sub>GS</sub> = -10V	-20			A
Drain-Source On-Resistance	R <sub>Ds(on)</sub>	V <sub>GS</sub> = -10V, I <sub>D</sub> =-10A		28	35	mΩ
		V <sub>GS</sub> = -4.5V, I <sub>D</sub> =-6A		36	45	
Forward Transconductance	g <sub>FS</sub>	V <sub>DS</sub> = -15V, I <sub>D</sub> = -5A		20		S
Diode Forward Voltage	V <sub>SD</sub>	I <sub>S</sub> = -2A, V <sub>GS</sub> =0V		-0.8	-1.2	V
<b>Dynamic</b>						
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =-20V, V <sub>GS</sub> =-4.5V I <sub>D</sub> = -5.0A		13	20	nC
Gate-Source Charge	Q <sub>gs</sub>			4.5		
Gate-Drain Charge	Q <sub>gd</sub>			6.5		
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =-20V, V <sub>GS</sub> =0V f=1MHz		1100		pF
Output Capacitance	C <sub>oss</sub>			145		
Reverse Transfer Capacitance	C <sub>rss</sub>			115		
Turn-On Time	t <sub>d(on)</sub>	V <sub>DD</sub> =-20V, R <sub>L</sub> =4Ω I <sub>D</sub> ≡-5.0A, V <sub>GEN</sub> =-4.5V R <sub>G</sub> =1Ω		40	80	ns
	t <sub>r</sub>			55	100	
Turn-Off Time	t <sub>d(off)</sub>			30	60	
	t <sub>f</sub>			12	20	



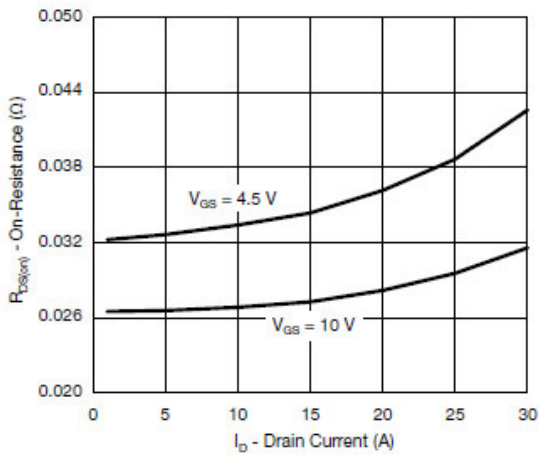
**Typical Characteristics ( N-Channel )**



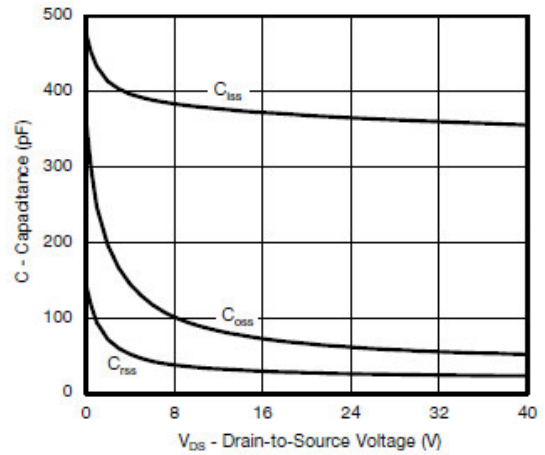
**Output Characteristics**



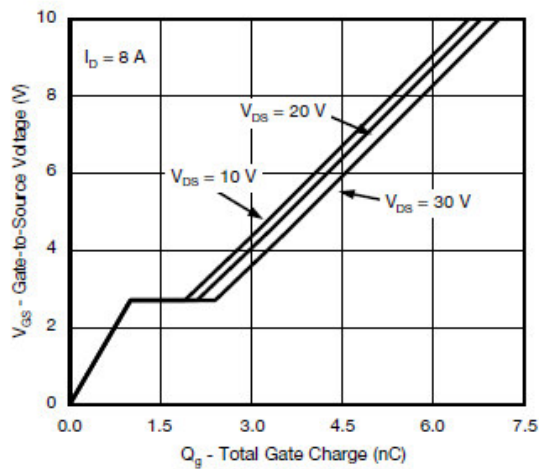
**Transfer Characteristics**



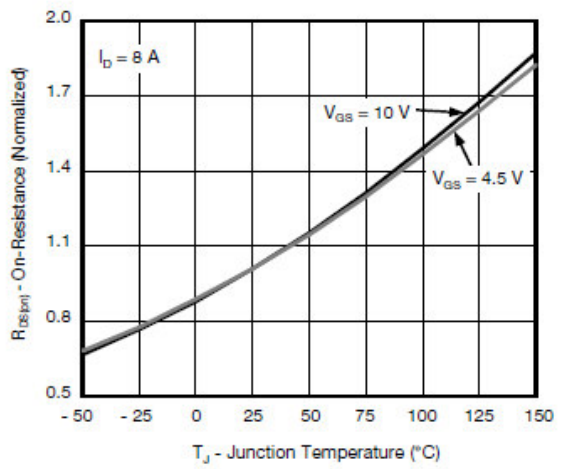
**On-Resistance vs. Drain Current**



**Capacitance**



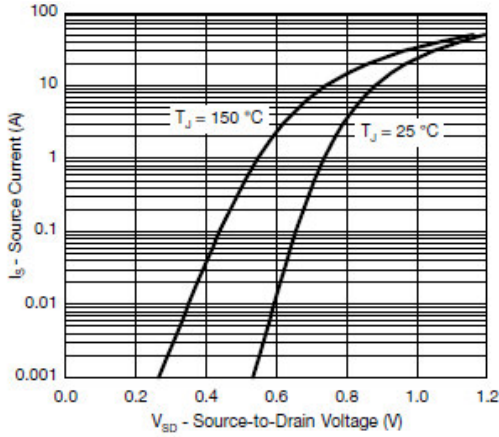
**Gate Charge**



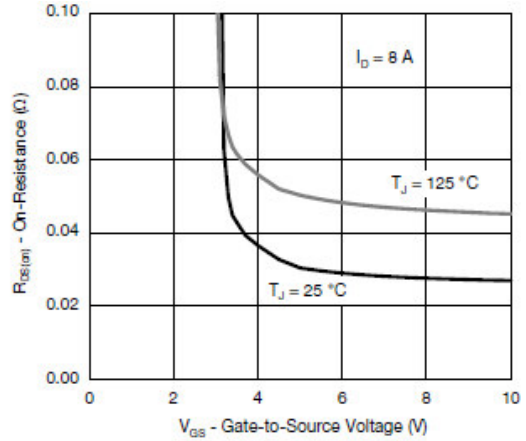
**On-Resistance vs. Junction Temperature**



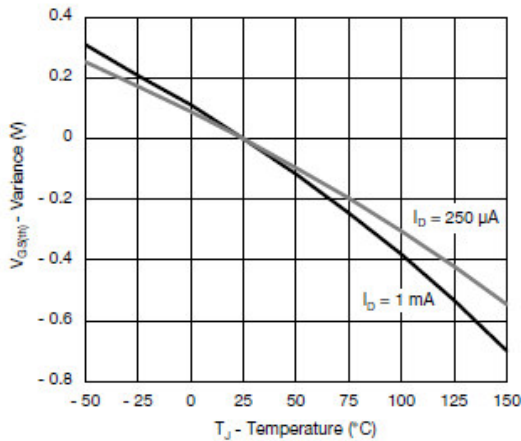
## Typical Characteristics ( N-Channel )



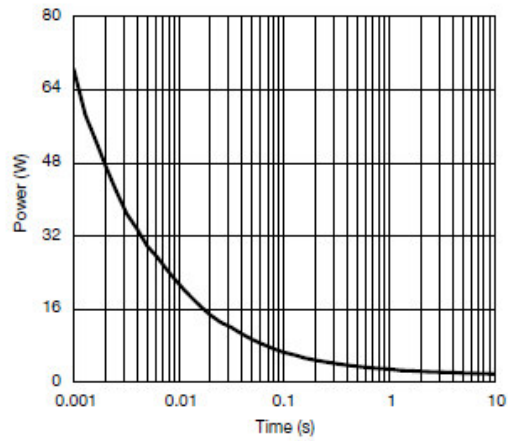
Source-Drain Diode Forward Voltage



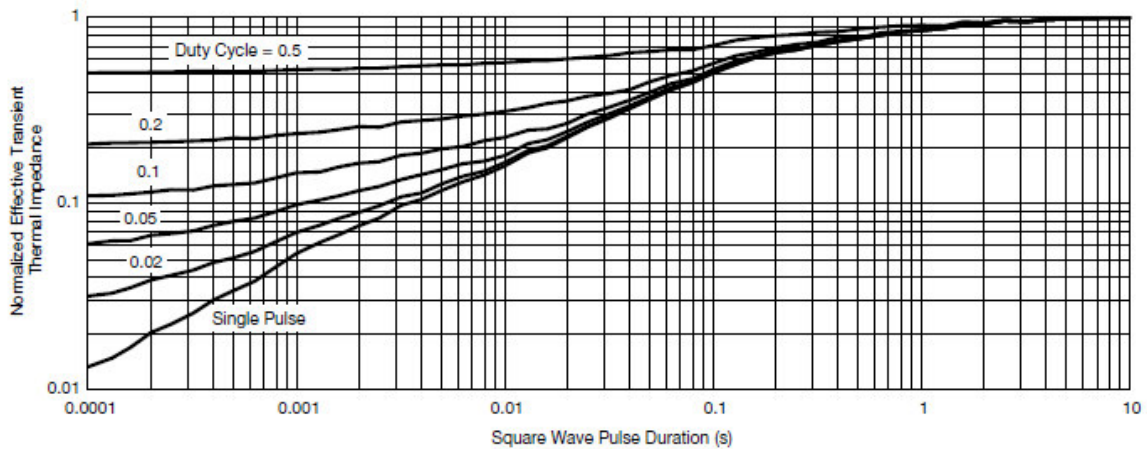
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage



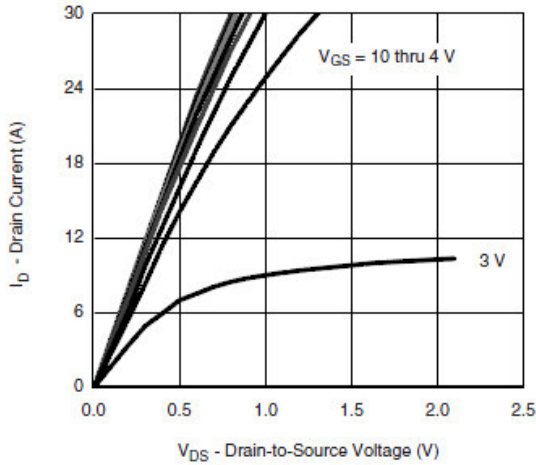
Single Pulse Power



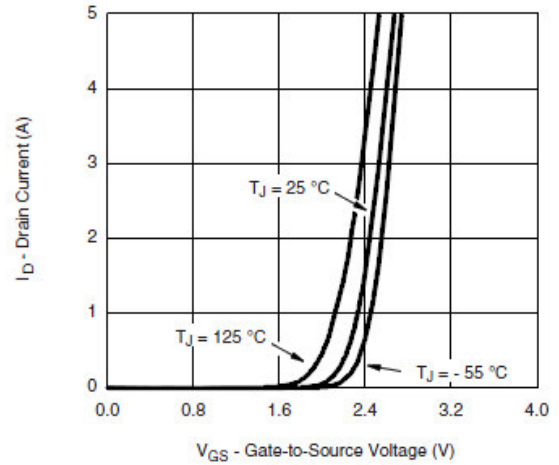
Normalized Thermal Transient Impedance, Junction-to-Foot



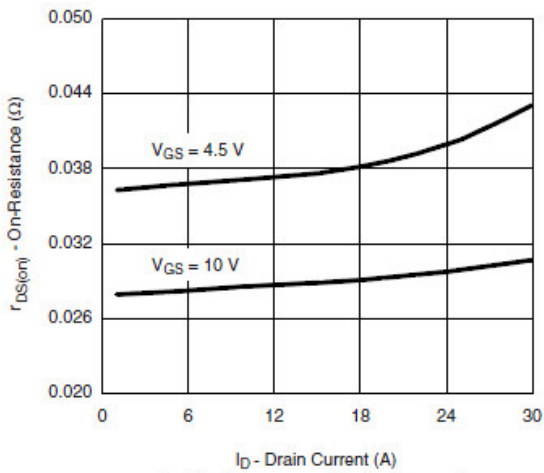
**Typical Characteristics ( P-Channel )**



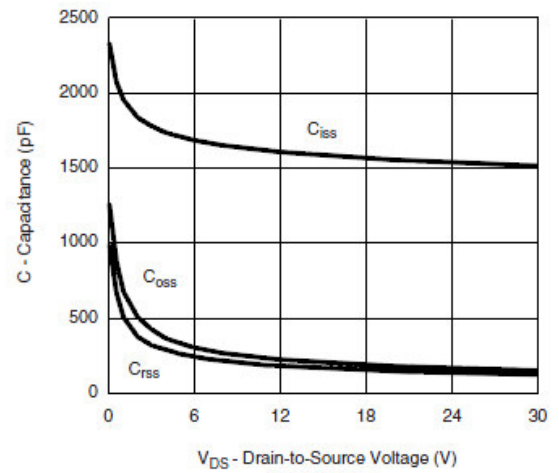
**Output Characteristics**



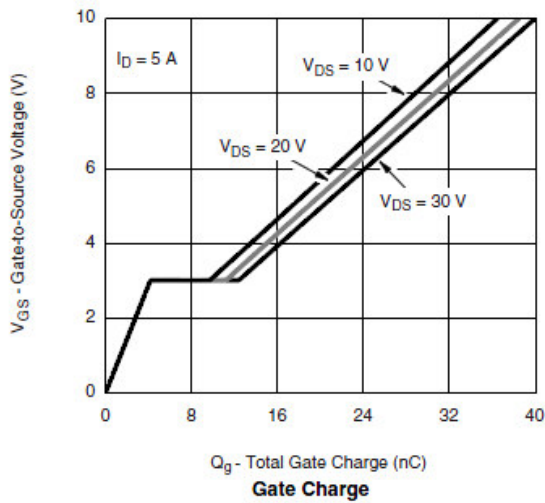
**Transfer Characteristics**



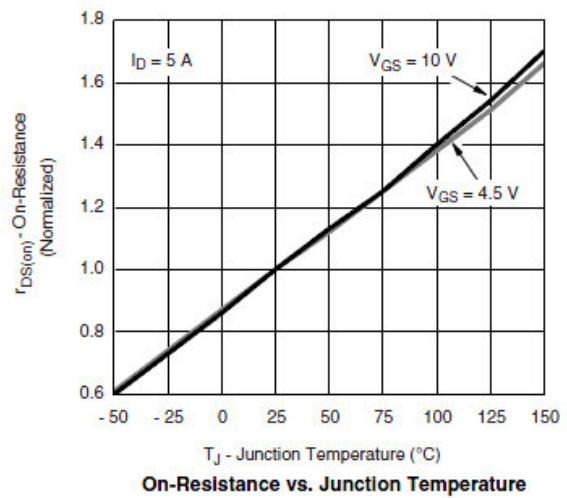
**On-Resistance vs. Drain Current**



**Capacitance**



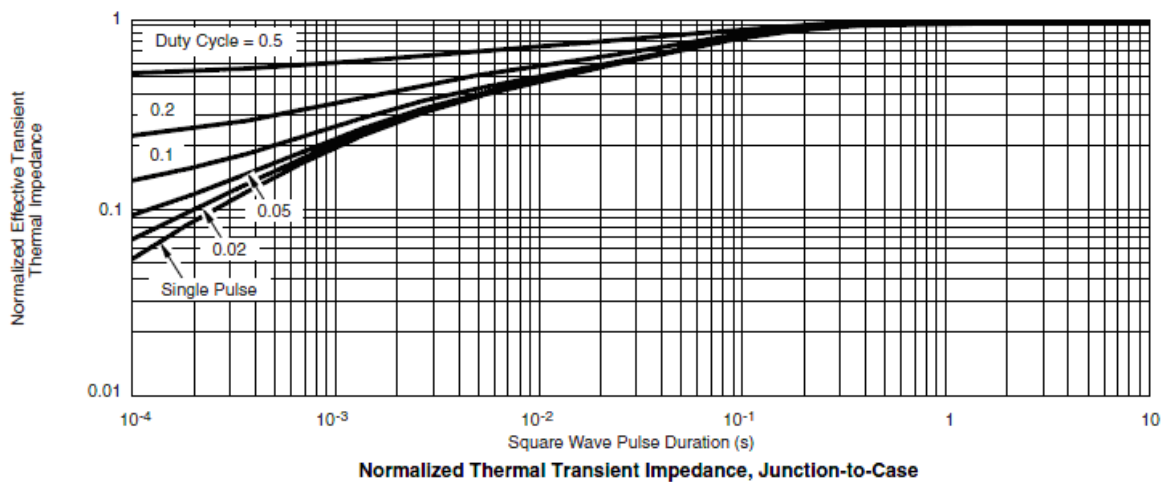
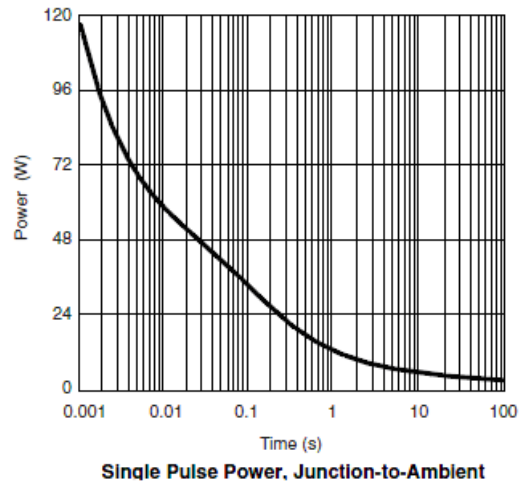
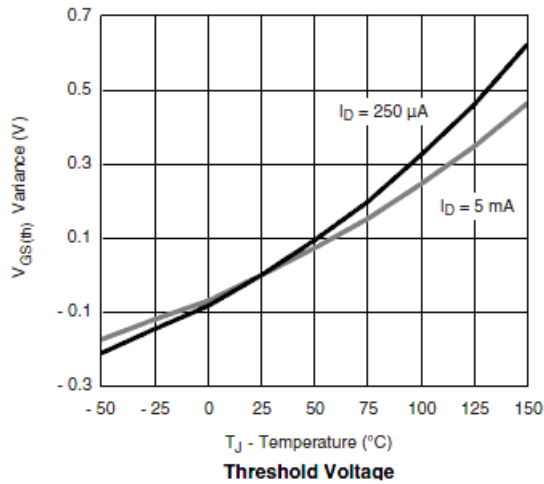
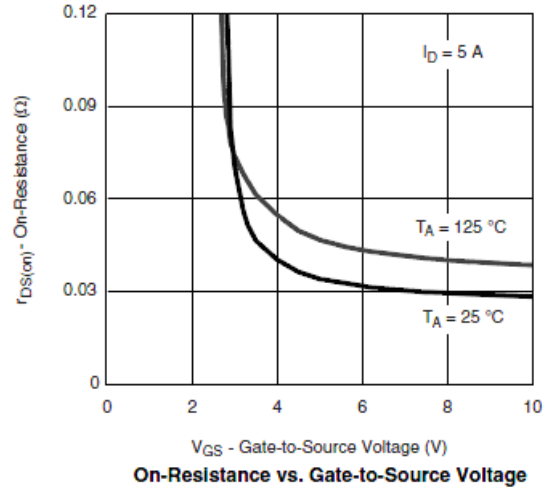
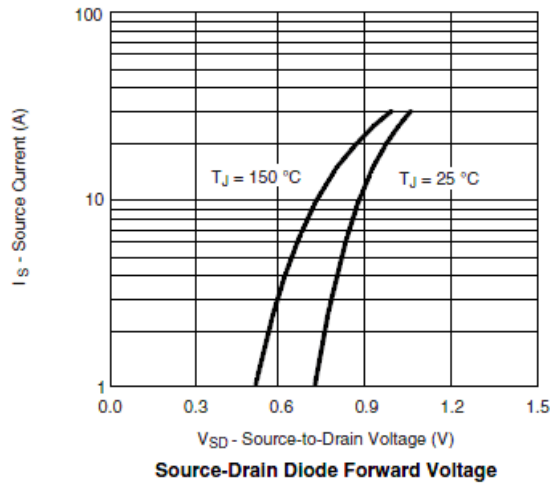
**Gate Charge**



**On-Resistance vs. Junction Temperature**



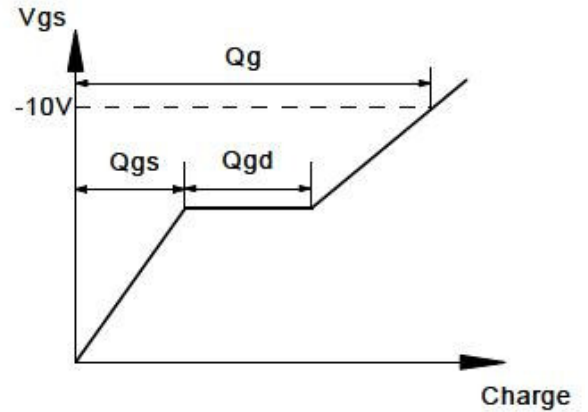
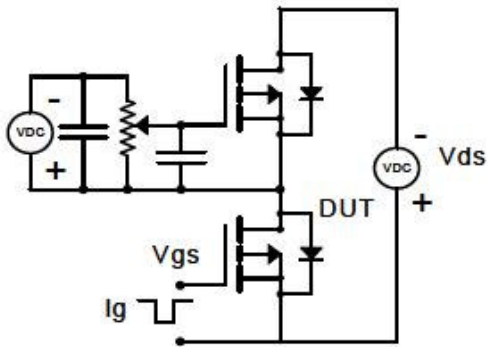
## Typical Characteristics ( P-Channel )



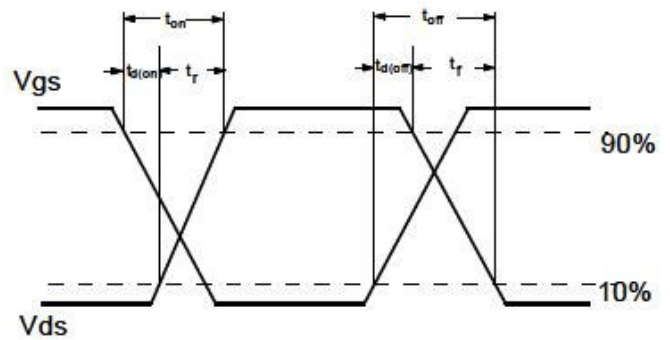
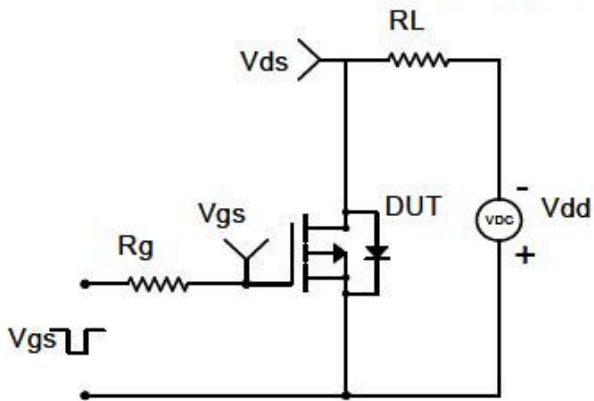


**Typical Characteristics**

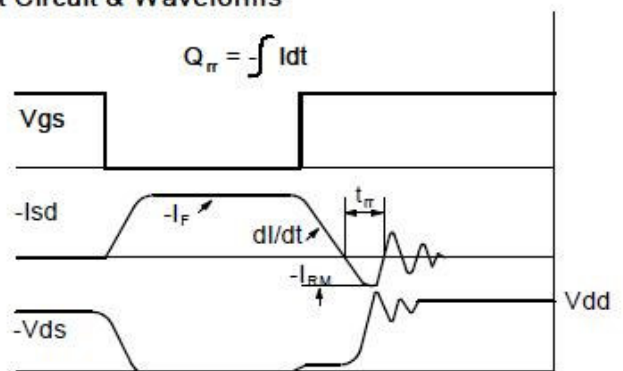
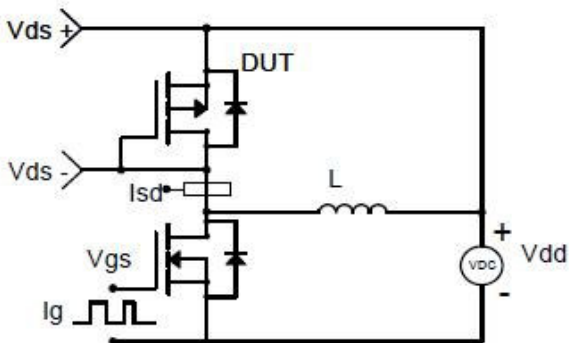
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms



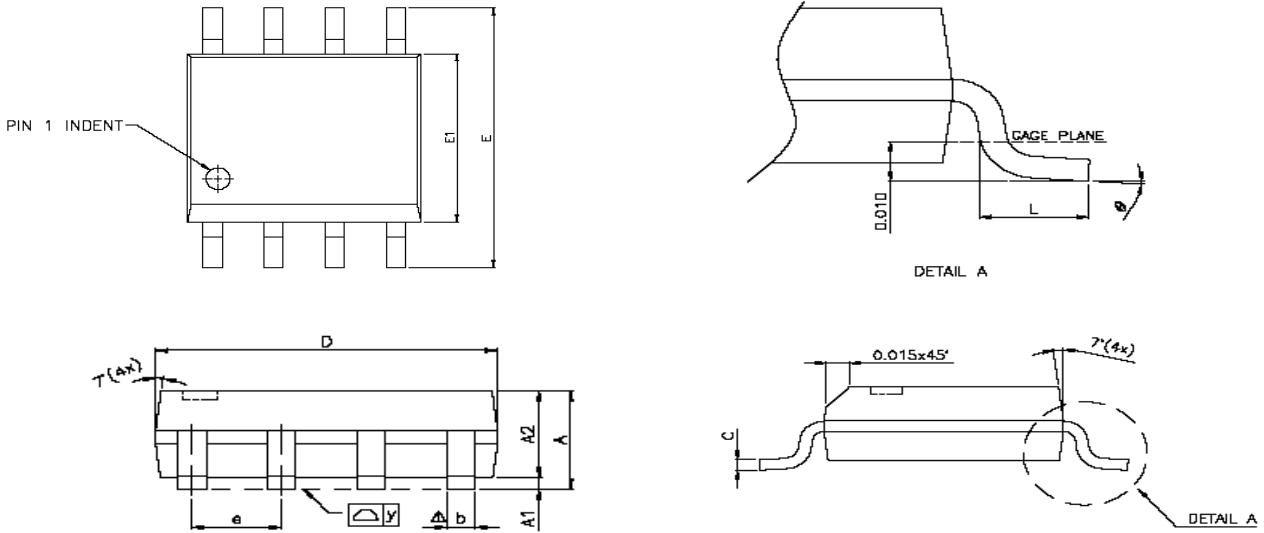
Diode Recovery Test Circuit & Waveforms







**Package Information ( SOP-8P )**



SYMBOLS	DIMENSIONS IN MILLIMETERS			DIMENSIONS IN INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	1.47	1.60	1.73	0.058	0.063	0.068
A1	0.10	—	0.25	0.004	—	0.010
A2	—	1.45	—	—	0.057	—
b	0.33	0.41	0.51	0.013	0.016	0.020
C	0.19	0.20	0.25	0.0075	0.008	0.0098
D	4.80	4.85	4.95	0.189	0.191	0.195
E	5.80	6.00	6.20	0.228	0.236	0.244
E1	3.80	3.90	4.00	0.150	0.154	0.157
e	—	1.27	—	—	0.050	—
L	0.38	0.71	1.27	0.015	0.028	0.050
$\Delta$ y	—	—	0.076	—	—	0.003
$\varnothing$	0°	—	8°	0°	—	8°

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